

## APPLICATION DATA SHEET

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22204

\*22204\*

*Application Information:*

Title of Invention: SOLDER BALL, METHOD OF MAKING THE SAME, AND  
METHOD OF MAKING SEMICONDUCTOR INTERCONNECT  
STRUCTURE

Application Type: regular, utility

Attorney Docket Number: 743421-82

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*Representative Information:*

practitioner(s) at Customer Number:

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact  
all business in the United States Patent and Trademark Office connected therewith.

*Domestic Priority Information:*

This is a National Stage of JP application number PCT/JP03/12183, filed 2003-09-24, now  
Pending.

*Foreign Priority Information:*

Doc.No:2002-283301; Country - JP; Date: 2002-09-27 us-priority-claimed

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